

List of references

10    Sensor chip  
12, 12a, 12b    Sensor element  
Z1 to Z16       Row  
S1 to S16       Column  
20    Detail  
22    Glass plate  
22a, 22b    Glass plate regions  
24    Wafer layer  
24a, 24a    Wafer region  
26    Adhesive layer  
28a, 28b    pin diode  
30    Interconnect  
32    Pad  
34    Outer interconnect  
36a, 36b    Solder pellet  
38    Contact area  
40b    Glass plate region  
42    Adhesive layer  
44a, 44b    Solder pellet  
46    Contact area  
50    Scintillator block  
52    Adhesive layer  
54a, 54b    Conversion regions  
56 to 60    Reflecting regions  
80    Filling material  
100    Semiconductor wafer  
D1, D2    Thickness  
102    Passivation layer  
104    Metallization layer  
106    Boundary  
108 to 114    Solder pads  
120    Cut  
122, 124    Region  
130    Metallization layer  
140    Passivation layer

1/7

Figure 1

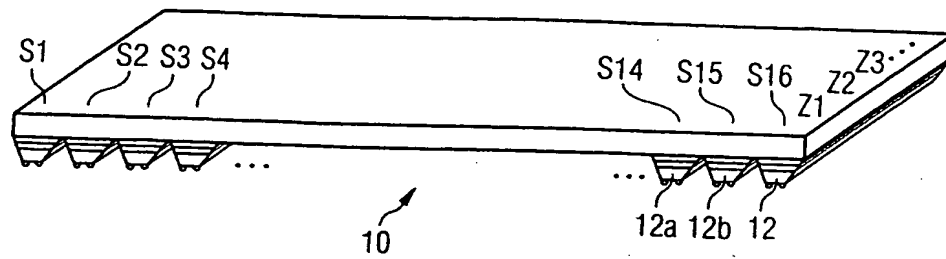
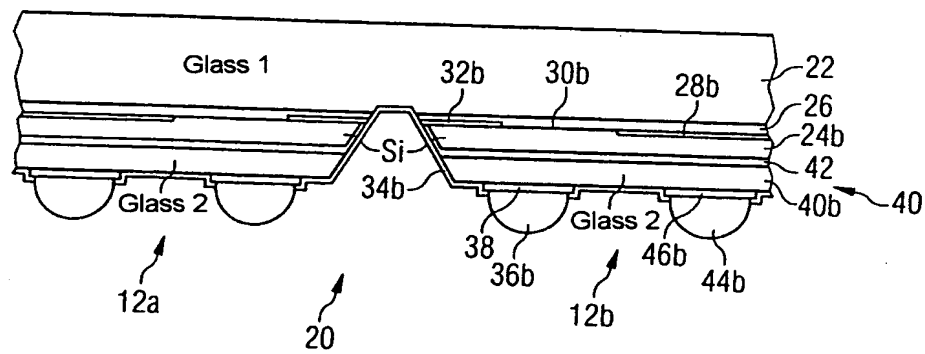


Figure 2



### Figure 3

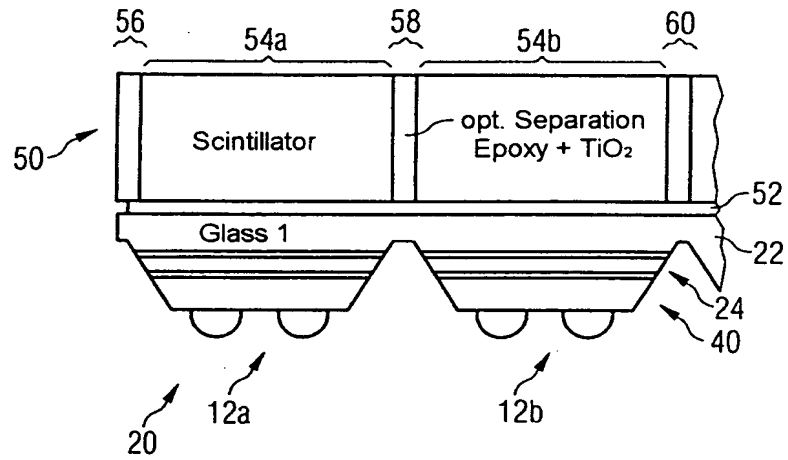
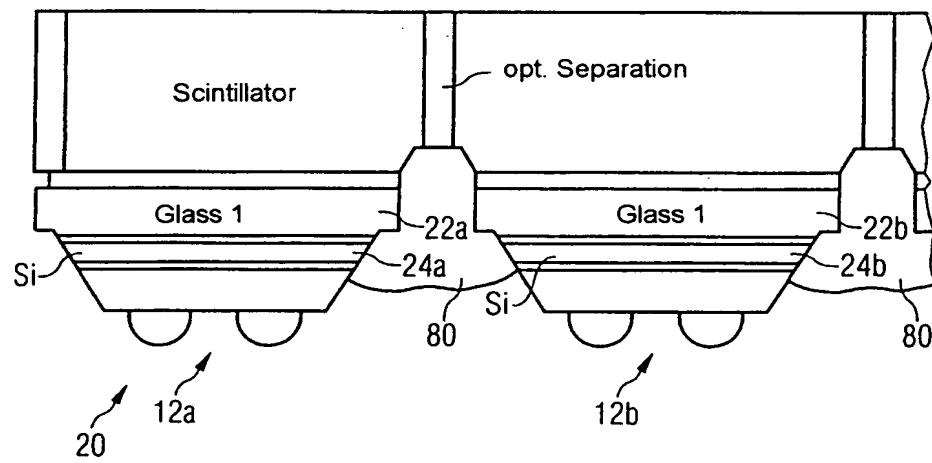


Figure 4



3/7

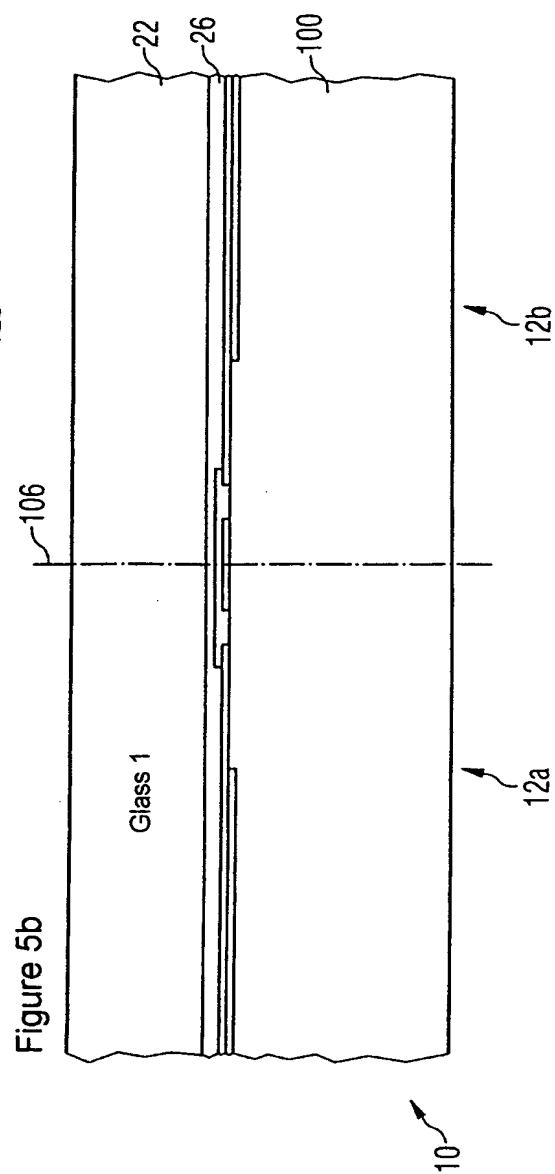
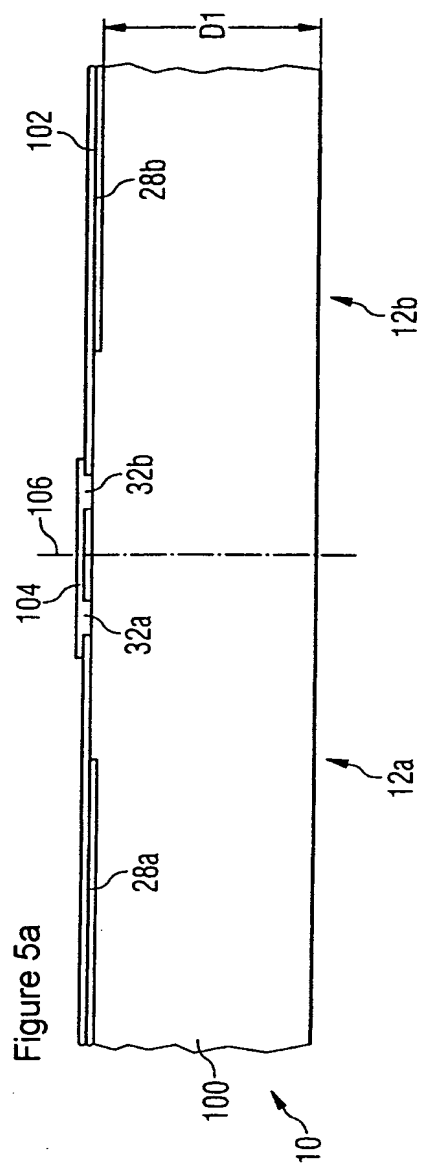


Figure 5C

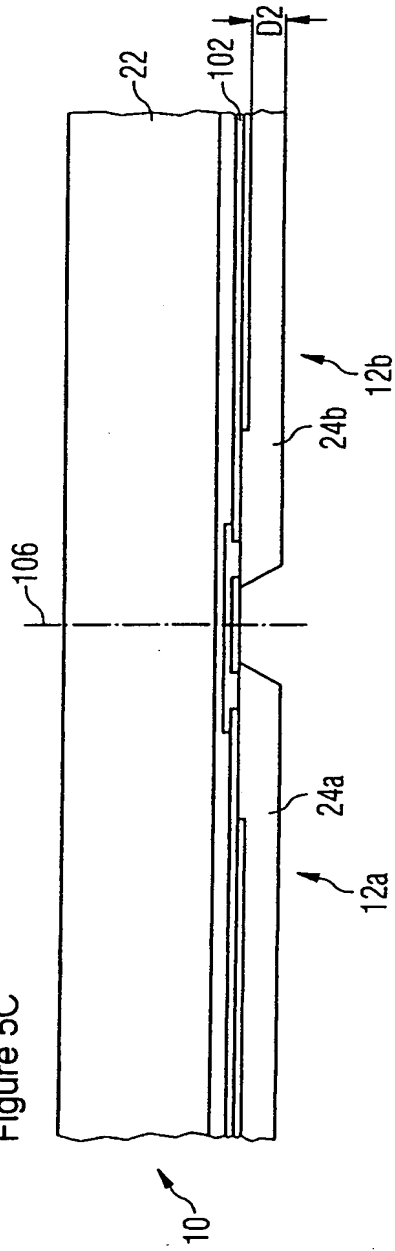
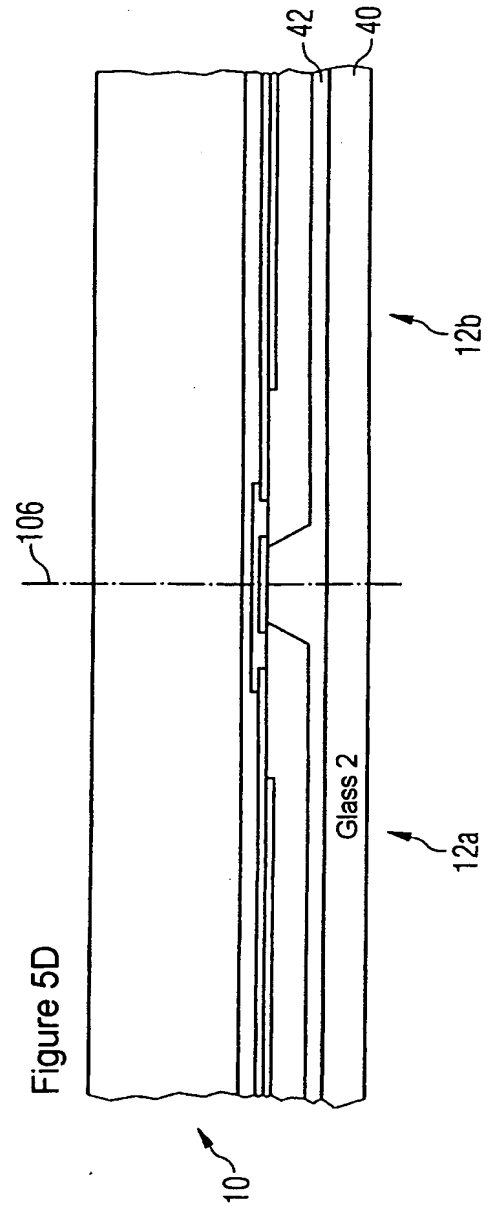


Figure 5D



5/7

Figure 5E

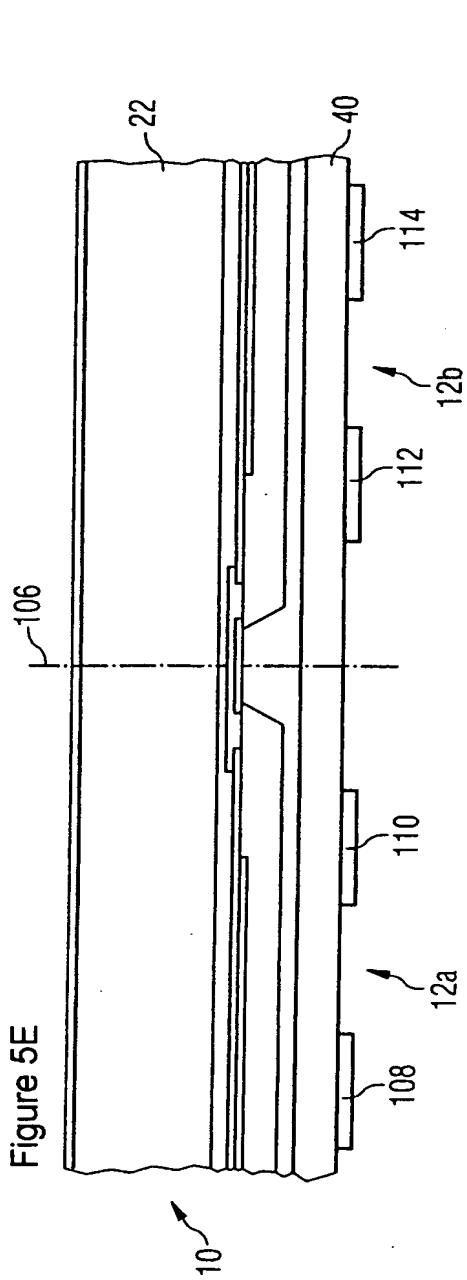


Figure 5F

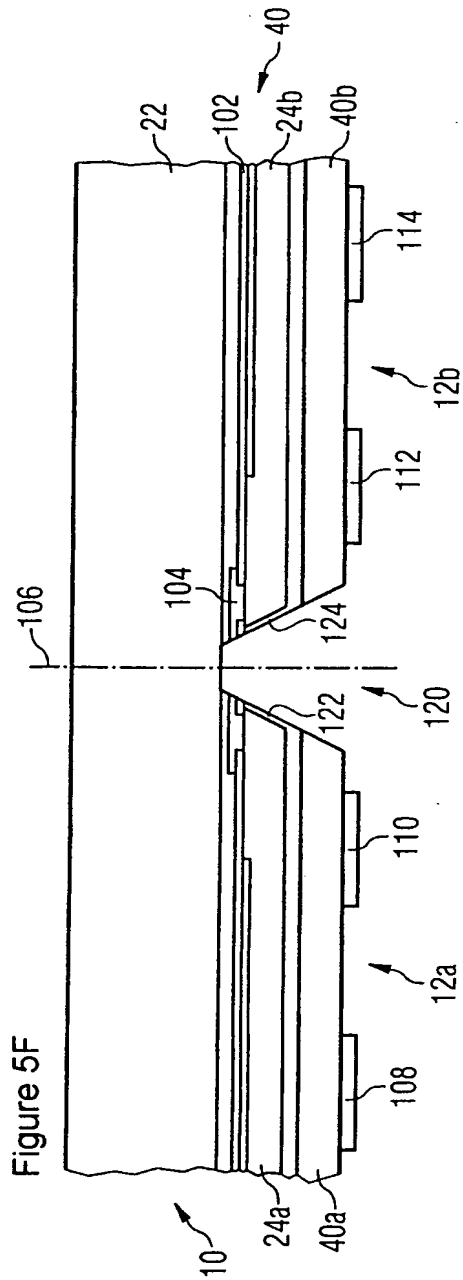


Figure 5G

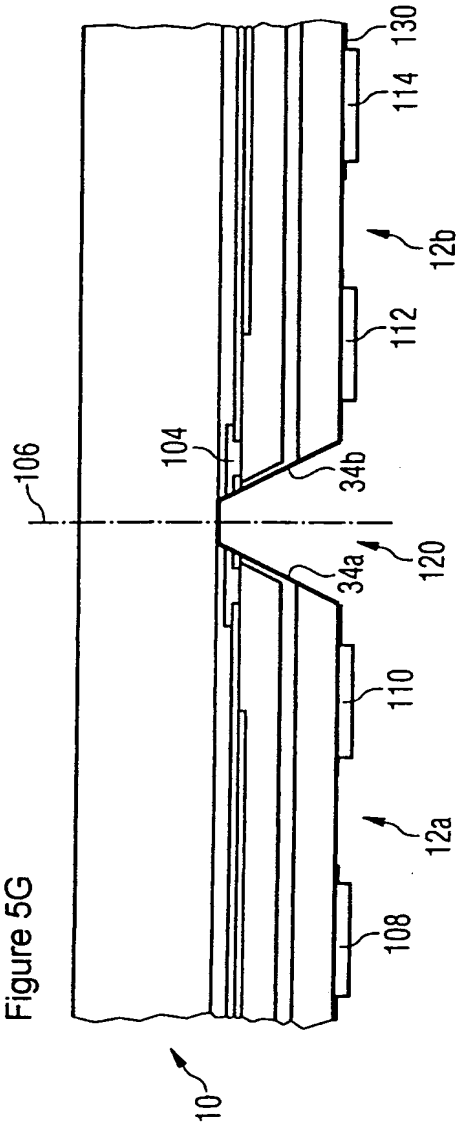
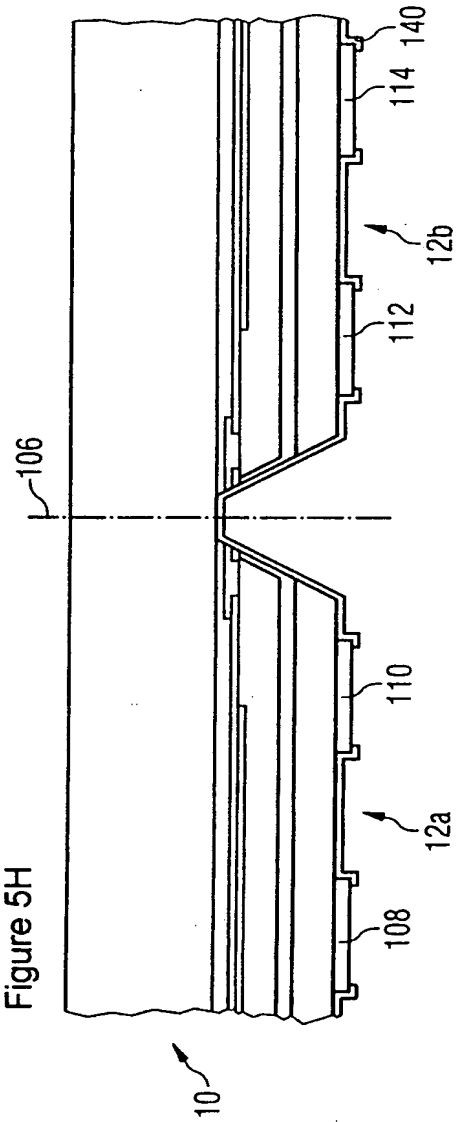


Figure 5H



7/7

